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To the Director of the U.S. Patent and Tra 102	921557 ents or the new address(es) below.
1. Name of conveying party(ies)/Execution Date(s):	2. Name and address of receiving party(ies)
Han-Choon LEE	Name: DongbuAnam Semiconductor Inc.
Jin-Woo PARK	Internal Address:
Execution Date(s) 12-23-2004	Street Address: 891-10, Daechi-dong, Kangnam-ku
Additional name(s) of conveying party(ies) attached? Yes 🗸 No	officer Address. Street Address.
3. Nature of conveyance:	
✓ Assignment	City: Scoul
OPP041456US Security Agreement Change of Name	Ctata
Government Interest Assignment	State:
Executive Order 9424, Confirmatory License	Country: KOREA Zip: 135-523
Other	Additional name(s) & address(ss) attached 0 Vos V No
	Additional name(s) & address(es) attached? Yes Volument is being filed together with a new application
A. Patent Application No.(s)	B. Patent No.(s)
τ,	
	tached? Yes No
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Andrew D. Fortney, Ph.D.	
Internal Address: The Law Offices of Andrew D. Fortney, Ph.D., P.C.	7. Total fee (37 CFR 1.21(h) & 3.41) \$_40
Internal Address:	· -
7077111 1 1 7 7 107	Authorized to be charged to deposit account
Street Address: 7257 N. Maple Avenue, Suite 107	Enclosed
	None required (government interest not affecting title
City: Fresno	8. Payment Information
State: CA Zip: 93720	a. Credit Card Last 4 Numbers 1447 Expiration Date 02/05
Phone Number:559-299-0128	
Fax Number: 559-299-0118	b. Deposit Account Number
Email Address: drew@fortneylaw.com	Authorized User Name
9. Signature:	12-30-2004
Signature	
Andrew D. Fortney, Ph.D., Reg. No. 34,600	Total number of pages including cover
Name of Person Signing	sheet, attachments, and documents:
	et) should be faxed to (703) 306-5995, or mailed to: of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450
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PATENT REEL: 016154 FRAME: 0595 Attorney Docket No.: OPP041456US

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, the undersigned,

LEE, Han-Choon PARK, Jin-Woo

who have created a certain invention for which an application for United States Letters Patent was executed by me concurrently herewith and entitled:

Method of forming plug of semiconductor device

at891-10, Dacchi-dong, Kangnam-ku, Seoul, 135-523, Korea	Do nereby sell, assign and transfer to Dongbuariam Semiconductor Inc.	
legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties; including all future conventions, unions, agreements, acts, and treaties; Agree that DongbuAnam Semiconductor Inc	of Korea , having a place of business	3
inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties; helding all future conventions, unions, agreements, acts, and treaties; Agree that DongbuAnam Semiconductor Inc. Agree that Consumations, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives and Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rig	at 891-10, Daechi-dong, Kangnam-ku, Seoul, 135-523, Korea, 1ts successors, assigns, and	1
United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties; heliuding all future conventions, unions, agreements, acts, and treaties; Agree that DongbuAnam Semiconductor Inc. Agree that DongbuAnam Semiconductor Inc. Agree that Organical Semiconductor	inventions described in said application for the United States, its territorial possessions and all foreign countries	,
continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties; Agree that DongbuAnam Semiconductor Inc. hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned. IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below. Pull Name of Second Inventor, if any: Date: Mont		
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Inventor's Signature: Date: Month/Day/Year Dec. 23, 2004 Full Name of Second Inventor, if any: PARK, Jin-Woo Inventor's Signature: Date: Month/Day/Year Date: Month/Day/Year	IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below.	
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Full Name of Second Inventor, if any: PARK, Jin-Woo Inventor's Signature: Date: Month/Day/Year Dog 23 2004	LEE, Han-Choon	
Full Name of Second Inventor, if any: PARK, Jin-Woo Inventor's Signature: Date: Month/Day/Year		
Full Name of Second Inventor, if any: PARK, Jin-Woo Inventor's Signature: Date: Month/Day/Year	der fram Charm Dec. 23, 2004	
PARK, Jin-Woo Inventor's Signature: Date: Month/Day/Year		
Inventor's Signature: Date: Month/Day/Year	Full Name of Second Inventor, if any:	
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Customer No. 36872

RECORDED: 12/30/2004

PATENT REEL: 016154 FRAME: 0596